

TRANSMITTAL

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Title of Invention	METHOD OF FABRICATING CONTACT HOLES ON A SEMICONDUCTOR CHIP						
<div>Application Number :</div> <div>Date :</div> <div>First Named Applicant: Kuo-Chien Wu</div> <div>Confirmation Number:</div> <div>Attorney Docket Number: NTCP0006USA</div>							
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Submitted By:	Elec. Sign.						
Winston Hsu Registered Number: 41,526	Winston Hsu						
Mord Michael Lewis Registered Number: 50,478	Mord Michael Lewis						

Documents being submitted:	Files
us-power-of-attorney-grant	NTCP0006-uspoat.xml us-power-of-attorney-grant.dtd us-power-of-attorney-grant.xsl
us-assignment	NTCP0006-usassn.xml us-assignment.xsl us-assignment.dtd NTCP0006ASS1.tif NTCP0006ASS2.tif
us-request	NTCP0006-usrequ.xml us-request.dtd us-request.xsl
us-fee-sheet	NTCP0006-usfees.xml us-fee-sheet.xsl us-fee-sheet.dtd
us-declaration	NTCP0006-usdecl.xml us-declaration.dtd us-declaration.xsl
us-declaration	NTCP0006DEC1.tif
us-declaration	NTCP0006DEC2.tif
application-body	NTCP0006-trans.xml us-application-body.xsl application-body.dtd wipo.ent mathml2.dtd mathml2-qname-1.mod isoamsa.ent isoamsb.ent isoamsc.ent isoamsn.ent isoamso.ent isoamsr.ent isogr3.ent isomfrk.ent isomopf.ent isomscr.ent isotech.ent isobox.ent isocyr1.ent isocyr2.ent isodia.ent isolat1.ent isolat2.ent isonum.ent isopub.ent mmlextra.ent mmlalias.ent soextblx.dtd ntcp006usa-01.tif ntcp006usa-02.tif

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Comments